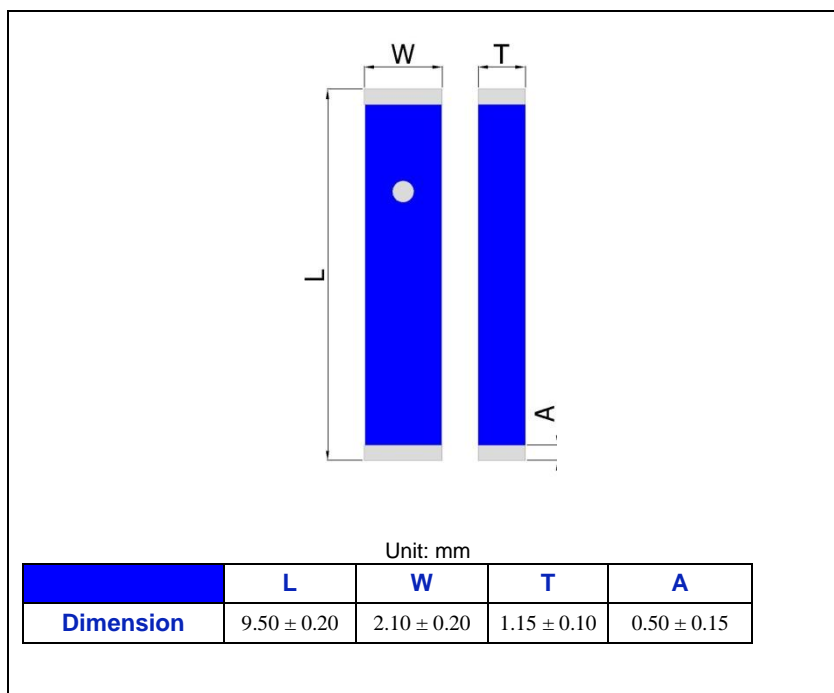


#### ELECTRICAL SPECIFICATION

SPECIFICATIONS	SPECIFICATIONS	UNIT
Working Frequency Range	2.4 ~ 2.5	GHz
Azimuth Bandwidth	Omni-directional	--
Gain, Typical	2	dBi
VSWR (Max)	2.0	--
Impedance	50	$\Omega$
Polarization	Linear	--
Rated Power (Max)	3	Watts
Maximum Input Power (for 5 minutes)	5	Watts
Operating Temperature	-40 to +125	$^{\circ}\text{C}$

#### MECHANICAL SPECIFICATION

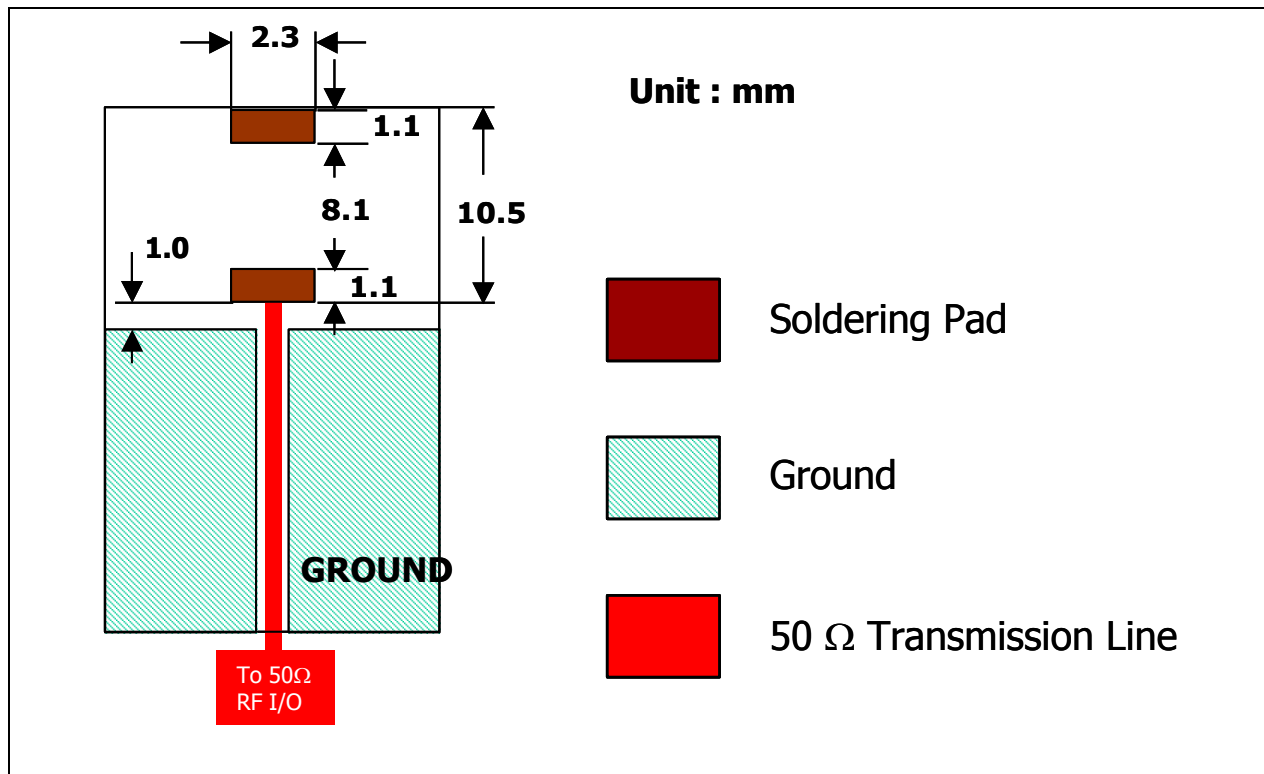


#### TOP VIEW



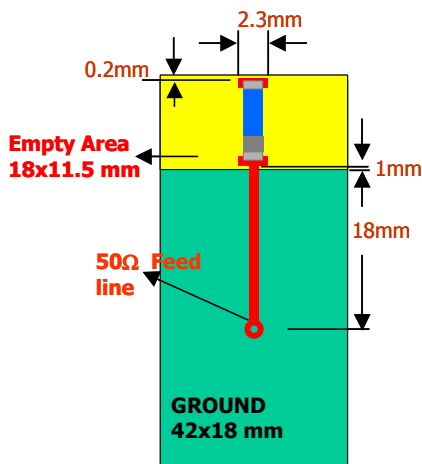
PIN	Connection
1	Feeding
2	Soldering terminal

#### ■ SOLDER LAND PATTERN DESIGN

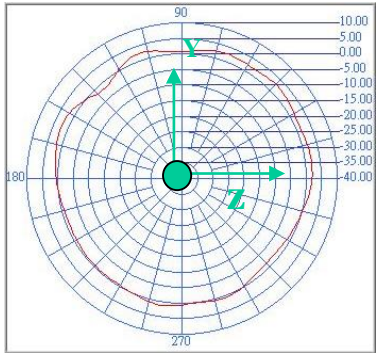
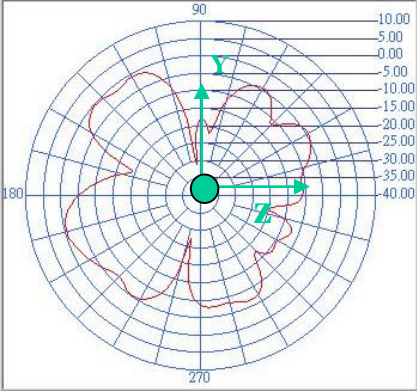
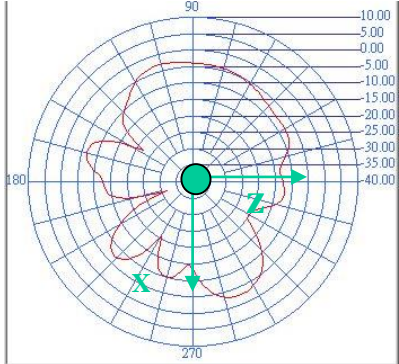
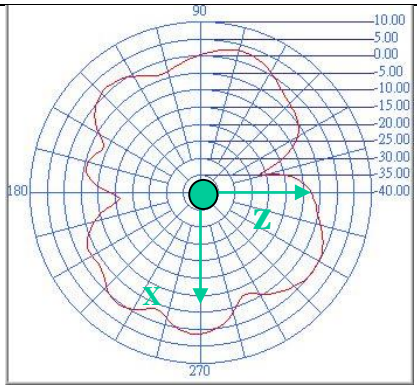
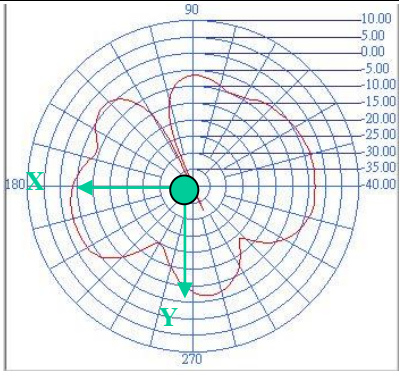
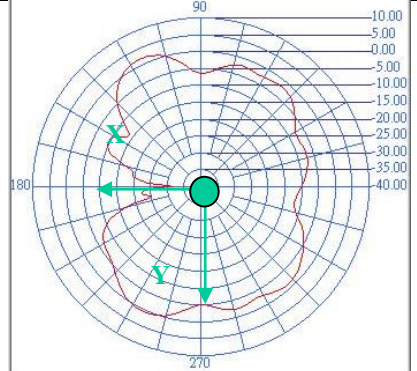


#### ■ RADIATION PATTERN

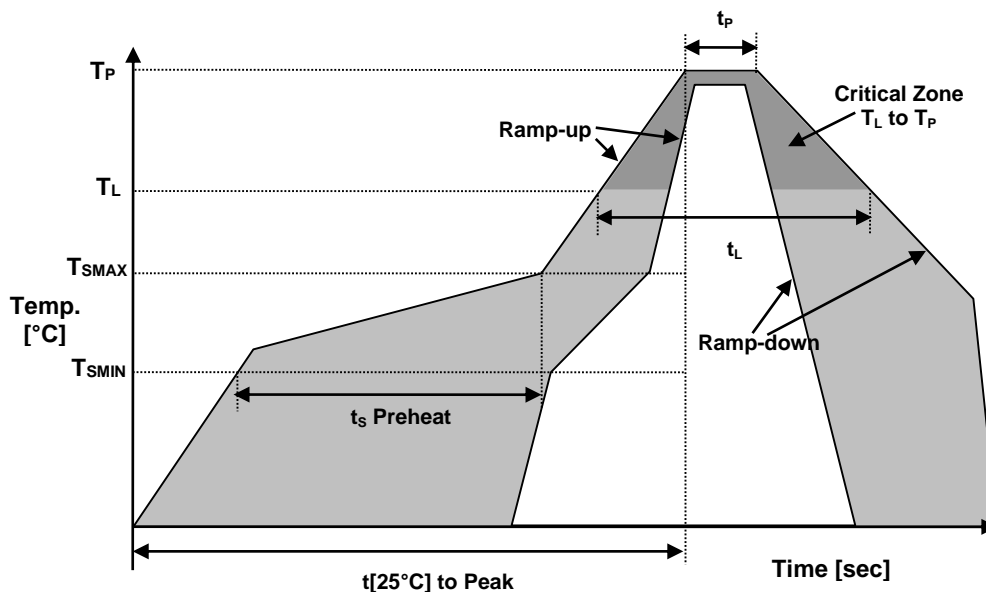
Radiation Pattern and Gain were dependent on board design based on the PCB size and installation position as shown in the below figure Test Board.



■ RADIATION PATTERN (Continued)

	Vertical	Horizontal
<b>Y - Z Plane</b>  Average Gain= 1.685 dBi	 <p>Peak Gain = 2.71 dBi Average Gain = 0.87 dBi</p>	 <p>Peak Gain= -0.30 dBi Average Gain=-5.98 dBi</p>
<b>X - Z Plane</b>  Average Gain= -0.844 dBi	 <p>Peak Gain= -2.69 dBi Average Gain= -7.65dBi</p>	 <p>Peak Gain= 2.97 dBi Average Gain= -1.86 dBi</p>
<b>X - Y Plane</b>  Average Gain= -1.801 dBi	 <p>Peak Gain= -2.66 dBi Average Gain= -6.40dBi</p>	 <p>Peak Gain= 1.82 dBi Average Gain= -3.65 dBi</p>

### REFLOW PROFILE



Reflow profile		
Temperature Min Preheat	$T_{SMIN}$	150°C
Temperature Max Preheat	$T_{SMAX}$	200°C
Time ( $T_{SMIN}$ to $T_{SMAX}$ )	$t_s$	60-180 sec.
Temperature	$T_L$	217°C
Peak Temperature	$T_P$	250°C
Ramp-up rate	$R_{UP}$	3°C/sec max.
Ramp-down rate	$R_{DOWN}$	6°C/sec max.
Time within 5°C of Peak Temperature	$t_p$	10 sec.
Time $t_{[25^\circ\text{C}]}$ to Peak Temperature	$t_{[25^\circ\text{C}] \text{ to Peak}}$	480 sec.
Time	$t_L$	60-150 sec.

### ENVIRONMENTAL

PARAMETER	VALUE
MOISTURE SENSITIVITY LEVEL	1
RoHS2	6/6 COMPLIANT & LEAD FREE
REACH-SVHC	COMPLIANT
HALOGEN-FREE	COMPLIANT
TERMINATION FINISH	Au



May, 2016